

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS:

1-73. (Canceled)

74. (New) An RFID tag, comprising:

a first substrate having oppositely facing first and second surfaces;

a second substrate having oppositely facing first and second surfaces,
the first surface of the second substrate facing the second surface of the first
substrate;

an RFID integrated circuit fixed to the first substrate so that the RFID
integrated circuit and the first substrate together form an RFID integrated circuit
module;

an RFID antenna disposed on the first surface of the second substrate
and electrically coupled to the RFID integrated circuit via a non-contact coupling;

an electrically conductive region disposed on the second surface of the
second substrate and electrically coupled to the RFID integrated circuit via a non-
contact coupling;

an adhesive layer between a surface of the RFID integrated circuit
facing the second substrate and the first surface of the second substrate, the
adhesive layer attaching the RFID integrated circuit module to the second substrate;
and

an attachment layer on the second surface of the second substrate for attaching the second substrate to a receiving surface.

75. (New) An RFID tag, comprising:
- a first substrate having oppositely facing first and second surfaces;
 - a second substrate having oppositely facing first and second surfaces, the first surface of the second substrate facing the second surface of the first substrate;
 - an RFID integrated circuit fixed to the first substrate so that the RFID integrated circuit and the first substrate together form an RFID integrated circuit module;
 - an RFID antenna disposed on the second surface of the second substrate and electrically coupled to the RFID integrated circuit via a non-contact coupling;
 - an adhesive layer between a surface of the RFID integrated circuit facing the second substrate and the first surface of the second substrate, the adhesive layer attaching the RFID integrated circuit module to the second substrate;
 - and
 - an attachment layer on the second surface of the second substrate for attaching the second substrate to a receiving surface.

76. (New) The RFID tag of claim 74, further including an attachment modifying layer modifying the attachment of the electrically conductive region such that the electrically conductive region is disrupted if the second substrate is tampered or removed from the receiving surface.

77. (New) The RFID tag of claim 76, wherein the RFID integrated circuit is adapted to detect at least one electrical property of the electrically conductive region so that modifying the at least one electrical property of the electrically conductive region is detected by the RFID integrated circuit.

78. (New) The RFID tag of claim 74, further including at last one electrical coupling circuit on the first substrate and connected to the RFID integrated circuit, the at least one electrical coupling circuit facilitating the electrical coupling of the RFID integrated circuit to the electrically conductive region and the RFID antenna.

79. (New) The RFID tag of claim 74, wherein the RFID antenna is disposed on the first surface of the second substrate.

80. (New) The RFID tag of claim 74, wherein the RFID integrated circuit is disposed on the second surface of the first substrate.

81. (New) The RFID tag of claim 74, wherein the attachment layer is arranged between the electrically conductive region and the receiving surface.

82. (New) The RFID tag of claim 76, wherein the attachment modifying layer is arranged between the second surface of the second substrate and the electrically conductive region.

83. (New) The RFID tag of claim 76, wherein the attachment layer is a layer of adhesive and the attachment modifying layer is an adhesion modifying layer.

84. (New) The RFID tag of claim 77, wherein the RFID integrated circuit is adapted to record or transmit information representing the at least one electrical property of the electrically conductive region.

85. (New) The RFID tag of claim 74, further comprising a power source within the tag and coupled to the RFID integrated circuit.

86. (New) The RFID tag of claim 77, wherein the at least one electrical property is an electrical impedance value of the electrically conductive region.

87. (New) The RFID tag of claim 78, wherein the RFID tag includes an adhesion modifying layer associated with the adhesive layer, the adhesion modifying layer modifying adhesion of the RFID integrated circuit or the at least one electrical coupling circuit so that the RFID integrated circuit or the at least one electrical coupling circuits is modified if the first substrate is removed from the second substrate.

88. (New) The RFID tag of claim 74, wherein the non-contact coupling is a capacitive coupling or an inductive coupling.

89. (New) The RFID tag of claim 75, wherein the integrated circuit is disposed on the second surface of the first substrate.

90. (New) The RFID tag of claim 75, further including an attachment modifying layer modifying the attachment of the electrically conductive region such that the electrically conductive region is disrupted if the second substrate is tampered or removed from the receiving surface.

91. (New) The RFID tag of claim 90, wherein the attachment layer is a layer of adhesive and the attachment modifying layer is an adhesion modifying layer.

92. (New) The RFID tag of claim 75, further comprising a power source within the tag and coupled to the RFID integrated circuit.

93. (New) The RFID tag of claim 75, wherein the adhesive layer is a first adhesive layer, and the RFID tag includes a second adhesive layer securing the RFID integrated circuit to the first substrate, and an adhesive modifying layer modifying adhesion of the RFID integrated circuit so that the RFID integrated circuit is modified if the RFID integrated circuit is removed from the first substrate.

94. (New) The RFID tag of claim 75, wherein the non-contact coupling is a capacitive coupling or an inductive coupling.

95. (New) The RFID tag of claim 79, wherein integrated circuit is disposed on the second surface of the first substrate.

96. (New) The RFID tag of claim 79, further comprising a power source within the tag and coupled to the RFID integrated circuit.

97. (New) The RFID tag of claim 79, wherein the adhesive layer is a first adhesive layer, and the tag includes a second adhesive layer securing the RFID integrated circuit to the first substrate, and an adhesive modifying layer modifying adhesion of the RFID integrated circuit so that the RFID integrated circuit is modified if the RFID integrated circuit is removed from the first substrate.

98. (New) The RFID tag of claim 79, wherein the non-contact coupling is a capacitive coupling or an inductive coupling.

99. (New) The RFID tag of claim 74, wherein the adhesive layer is a first adhesive layer, and the RFID tag includes a second adhesive layer securing the RFID integrated circuit to the first substrate, and an adhesive modifying layer modifying adhesion of the RFID integrated circuit so that the RFID integrated circuit is modified if the RFID integrated circuit is removed from the first substrate.

100. (New) The RFID tag of claim 74, wherein a surface area of the second surface of the first substrate is smaller than a surface area of the first surface of the second substrate.

101. (New) The RFID tag of claim 75, wherein a surface area of the second surface of the first substrate is smaller than a surface area of the first surface of the second substrate.

102. (New) The RFID tag of claim 74, further comprising an adhesion modifying layer between the second surface of the first substrate and the RFID integrated circuit.

103. (New) The RFID tag of claim 75, further comprising an adhesion modifying layer between the second surface of the first substrate and the RFID integrated circuit.

104. (New) A method of manufacturing an RFID tag, comprising:

- forming an RFID integrated circuit module by fixing an RFID integrated circuit to a first substrate having oppositely facing first and second surfaces;
- forming an RFID antenna on the first surface of a second substrate having oppositely facing first and second surfaces, the first surface of the second substrate facing the second surface of the first substrate;
- forming an electrically conductive region on the second surface of the second substrate; and
- attaching the RFID integrated circuit module to the second substrate via an adhesive layer between a surface of the RFID integrated circuit facing the second substrate and the first surface of the second substrate so that the RFID antenna is electrically coupled to the RFID integrated circuit via a non-contact coupling and the electrically conductive region is electrically coupled to the RFID integrated circuit via a non-contact coupling.

105. (New) A method of manufacturing an RFID tag, comprising:

forming an RFID integrated circuit module by fixing an RFID integrated circuit to a first substrate having oppositely facing first and second surfaces;

forming an RFID antenna on a surface of a second substrate, the second substrate facing the first substrate; and

attaching the RFID integrated circuit module to the second substrate via an adhesive layer between a surface of the RFID integrated circuit facing the second substrate and the second substrate so that the RFID antenna is electrically coupled to the RFID integrated circuit via a non-contact coupling.

106. (New) The method of claim 105, wherein the second substrate has a first surface facing the first substrate and a second surface opposite the first surface, and the RFID antenna is formed on the second surface of a second substrate.